CMOS Digital Integrated Circuits Silicon Monolithic

TC7PCI3212MT,TC7PCI3215MT

1. Functional Description

· 2 Differential Channel, 2:1 multiplexer/demultiplexer switch for PCI Express Gen3

2. General

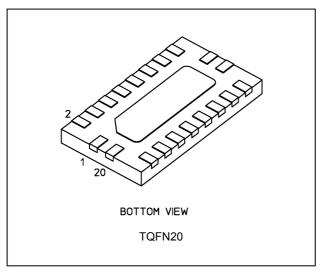
The TC7PCI3212MT and TC7PCI3215MT are 2 differential channel, 1-2 multiplexer/demultiplexer for PCI Express Gen3 (8Gbps), or other high-speed interface applications.

The An+/An- inputs is connected to the Bn+/Bn- or Cn+/Cn- outputs determined by the combination both the select input (SEL) and output enable (\overline{OE}) . When the output enable (\overline{OE}) input is held high-level, the switches are open (high-impedance state) with regardless the state of select inputs and reducing consumption current. All inputs are equipped with protection circuits against static discharge.

3. Features

- (1) Operating voltage: $V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$
- (2) Switch terminal ON-capacitance: $C_{I/O} = 1.5 \text{ pF}$ Switch On (typ.) $@V_{CC} = 3.3 \text{ V}$
- (3) ON resistance: $R_{ON} = 7.5 \Omega$ (typ.) @ $V_{CC} = 3.0 \text{ V}$, $V_{IS} = 0 \text{ V}$
- (4) -3dB Bandwidth: BW = 11.5 GHz (typ.) @ $V_{CC} = 3.3 \text{ V}$
- (5) Insertion Loss: DDIL = -1 dB (typ.) @ V_{CC} = 3.3 V, f = 4 GHz
- (6) Off Isolation: DDOIRR = -20 dB (typ.) @ V_{CC} = 3.3 V, f = 4 GHz
- (7) Crosstalk: DDNEXT = -40 dB (typ.) @ V_{CC} = 3.3 V, f = 4 GHz
- (8) ESD performance: Machine model $\geq \pm 200$ V, Human body model $\geq \pm 2000$ V
- (9) Package: TQFN20

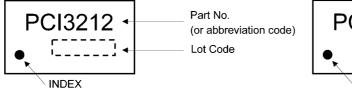
4. Packaging



5. Marking

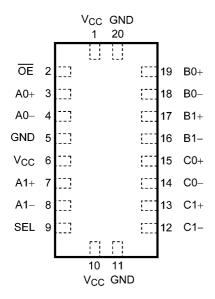
TC7PCI3212MT

TC7PCI3215MT

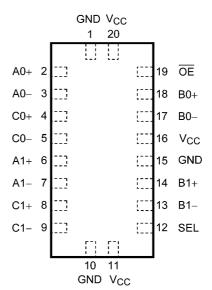


6. Pin Assignment

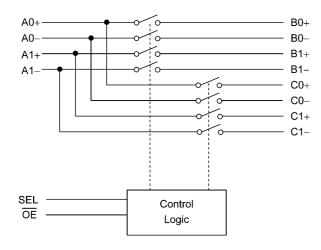
TC7PCI3212MT



TC7PCI3215MT



7. Block Diagram



8. Principle of Operation

8.1. Truth Table

| Inputs OE | Inputs SEL | Function | Function |
|--------------|---------------|--|----------|
| L | L | An+ port = Bn+ port, An- port = Bn- port | (n=0,1) |
| L | Н | An+ port = Cn+ port, An- port = Cn- port | (n=0,1) |
| Н | _ | An, Bn, Cn port Disconnect | (n=0,1) |

—: Don't care.



9. Absolute Maximum Ratings (Note)

| Characteristics | Symbol | Note | Rating | Unit |
|---------------------------------|-----------------------------------|------|------------------------------|------|
| Supply voltage | V_{CC} | | -0.5 to 4.6 | V |
| Input voltage (OE, SEL) | V _{IN} | | -0.5 to 4.6 | ٧ |
| Switch I/O voltage | V_S | | -0.5 to V _{CC} +0.5 | V |
| Switch I/O current | I _S | | 50 | mA |
| Power dissipation | P_{D} | | 500 | mW |
| V _{CC} /ground current | I _{CC} /I _{GND} | | ±50 | mA |
| Storage temperature | T _{stg} | | -55 to 125 | °C |

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

10. Operating Ranges (Note)

| Characteristics | Symbol | Note | Rating | Unit |
|-------------------------|------------------|------|----------------------|------|
| Supply voltage | V _{CC} | | 3.0 to 3.6 | V |
| Input voltage (OE, SEL) | V _{IN} | | 0 to 3.6 | V |
| Switch I/O voltage | V _S | | 0 to V _{CC} | V |
| Operating temperature | T _{opr} | | -40 to 85 | °C |
| Input rise time | dt/dv | | 0 to 10 | ns/V |
| Input fall time | dt/dv | | 0 to 10 | ns/V |

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused control inputs must be tied to either V_{CC} or GND.

11. Electrical Characteristics

11.1. DC Characteristics (Note) (Unless otherwise specified, Ta = -40 to 85 °C)

| Characteristics | Symbol | Note | Test Condition | V _{CC} (V) | Min | Тур. | Max | Unit |
|---|-----------------------|----------|---|---------------------|------------------------|------|------------------------|------|
| High-level input voltage (OE, SEL) | V _{IH} | | _ | 3.0 to 3.6 | 0.65 × V _{CC} | _ | _ | V |
| Low-level input voltage (OE, SEL) | V _{IL} | | _ | 3.0 to 3.6 | | _ | 0.35 × V _{CC} | V |
| Input leakage current (OE, SEL) | I _{IN} | | V _{IN} = 0 to 3.6 V | 3.0 to 3.6 | | | ±1 | μА |
| Switch OFF-state leakage current | I _{SZ} | | $\frac{V_{IS}}{OE} = 0 \text{ to } V_{CC},$ | 3.0 to 3.6 | | _ | ±1 | μА |
| ON-resistance | R _{ON} | (Note 1) | $V_{IS} = 0 \text{ V}, I_{IS} = 30 \text{ mA}$ | 3.0 | _ | 7.5 | 11.5 | Ω |
| | R _{ON} | (Note 1) | V _{IS} = 1.2 V, I _{IS} = 30 mA | 3.0 | _ | 8.5 | 13.5 | Ω |
| Difference of ON-resistance between switches (bit to bit) | ΔR _{ON} | (Note 1) | V _{IS} = 0 V, 1.2 V, I _{IS} = 15 mA | 3.0 | | 0.1 | _ | Ω |
| ON-resistance flatness | R _{ON(flat)} | (Note 1) | V _{IS} = 0 V to 1.2 V, I _{IS} = 15 mA | 3.0 | _ | 1 | _ | Ω |
| Quiescent supply current | I _{CC} | | $\frac{V_{IN}}{OE} = V_{CC}$ or GND, | 3.6 | | _ | 1 | μА |
| Quiescent supply current | I _{CC} | | $\frac{V_{IN}}{OE} = V_{CC} \text{ or GND},$ | 3.6 | _ | 200 | 500 | μА |

Note : All typical values are at $T_a = 25$ °C.

Note 1: ON-resistance is measured by measuring the voltage drop across the switch at the indicated current.



11.2. AC Characteristics (Note) (Unless otherwise specified, Ta = -40 to 85 °C)

| Characteristics | Symbol | Note | Test Condition | V _{CC} (V) | Min | Тур. | Max | Unit |
|----------------------------------|--|----------|---|---------------------|-----|------|-----|------|
| Propagation delay time | t _{PLH} / t _{PHL} | (Note 1) | $C_L = 5 \text{ pF}$ See Fig. 12.1 | 3.3 ± 0.3 | _ | 0.1 | _ | ns |
| Turn-ON time (SEL to Output) | t _{on} | | R_L = 50 Ω , C_L = 5 pF See Fig. 12.2 | 3.3 ± 0.3 | | 10 | 15 | ns |
| Turn-ON time (OE to Output) | t _{on} | | R_L = 50 Ω , C_L = 5 pF See Fig. 12.2 | 3.3 ± 0.3 | 1 | 37 | 50 | μS |
| Turn-OFF time (SEL to Output) | t _{off} | | R_L = 50 Ω , C_L = 5 pF See Fig. 12.2 | 3.3 ± 0.3 | | 3.5 | 5 | ns |
| Turn-OFF time (OE to Output) | t _{off} | | R_L = 50 Ω , C_L = 5 pF See Fig. 12.2 | 3.3 ± 0.3 | | 5 | 6.5 | ns |
| Break before make | TBBM | | R_L = 50 Ω , C_L = 5 pF See Fig. 12.3 | 3.3 ± 0.3 | 3 | _ | 9 | ns |
| Output skew (bit to bit) | t _{SK(b)} | (Note 1) | C_L = 5 pF See Fig. 12.4 | 3.3 ± 0.3 | | 5 | | ps |
| Output skew (channel to channel) | t _{SK(CH)} | (Note 1) | C_L = 5 pF See Fig. 12.5 | 3.3 ± 0.3 | | 10 | _ | ps |
| Differential OFF isolation | DDOIRR | (Note 1) | R_T = 50 Ω , f = 4 GHz See Fig. 12.6 | 3.3 ± 0.3 | _ | -20 | _ | dB |
| Differential Near-end crosstalk | DDNEXT | (Note 1) | R_T = 50 Ω , f = 4 GHz See Fig. 12.7 | 3.3 ± 0.3 | | -40 | 1 | dB |
| Differential return loss | DDRL | (Note 1) | R_T = 50 Ω , f = 4 GHz See Fig. 12.8 | 3.3 ± 0.3 | | -20 | | dB |
| Differential insertion loss | DDIL | (Note 1) | R_T = 50 Ω , f = 4 GHz See Fig. 12.8 | 3.3 ± 0.3 | _ | -1 | | dB |
| -3dB Bandwidth | BW | (Note 1) | $R_T = 50 \Omega$, $C_L = 0 pF$ See Fig. 12.8 | 3.3 ± 0.3 | | 11.5 | | GHz |

Note : All typical values are at $T_a = 25$ °C.

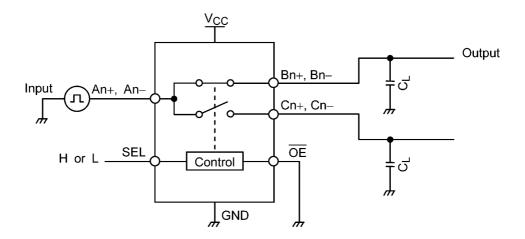
Note 1: This parameter is guaranteed by design.

11.3. Capacitive Characteristics (Note) (Unless otherwise specified, T_a = 25 °C)

| Characteristics | Symbol | Note | Test Condition | V _{CC} (V) | Тур. | Unit |
|--|------------------|------|--|---------------------|------|------|
| Input capacitance (OE, SEL) | C _{IN} | | V _{IN} = 0 V | 3.3 | 3 | pF |
| Switch terminal OFF-capacitance (An+, An-) | C _{I/O} | | $\overline{OE} = V_{CC}, V_{IS} = 0 V$ | 3.3 | 8.0 | pF |
| Switch terminal OFF-capacitance (Bn+, Bn-, Cn+, Cn-) | | | $\overline{OE} = V_{CC}, V_{IS} = 0 V$ | 3.3 | 0.5 | pF |
| Switch terminal ON-capacitance | C _{I/O} | | OE = GND, V _{IS} = 0 V | 3.3 | 1.5 | pF |

Note: Parameter guaranteed by design.

12. AC Electrical Test Circuit (Fig)



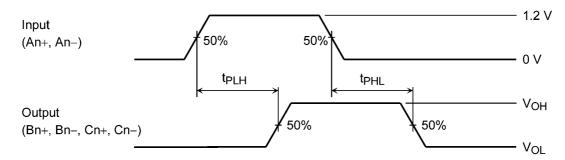
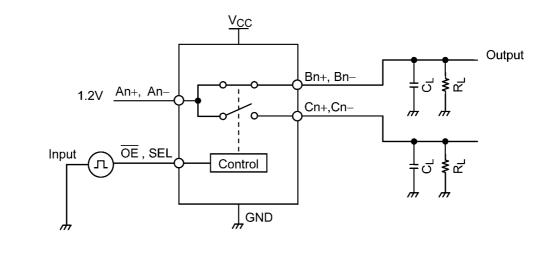


Fig. 12.1 Propagation delay time



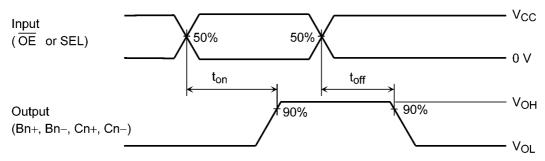


Fig. 12.2 Turn-ON and Turn-OFF time

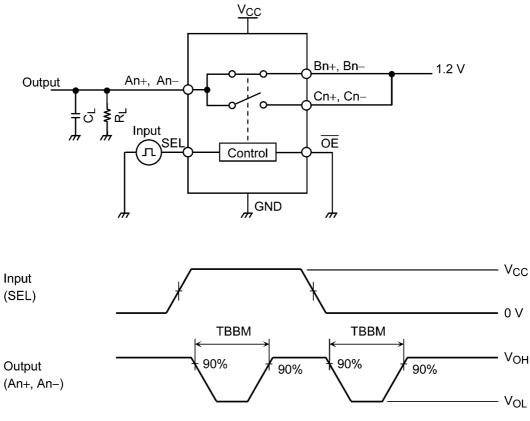
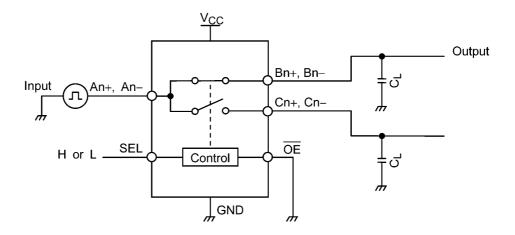


Fig. 12.3 Break before make



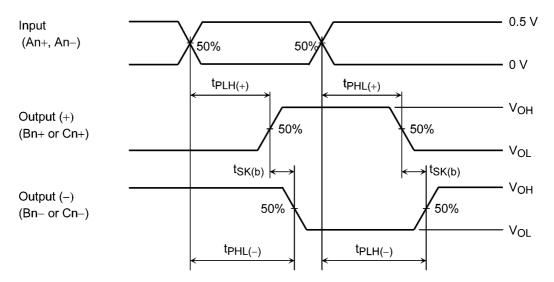


Fig. 12.4 Output skew (bit to bit)

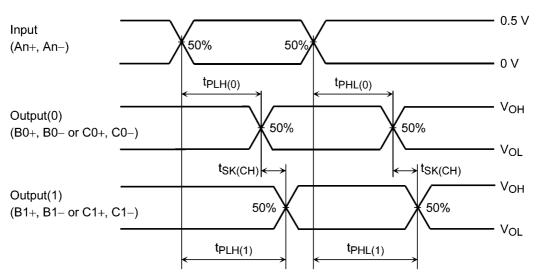


Fig. 12.5 Output skew (channel to channel)

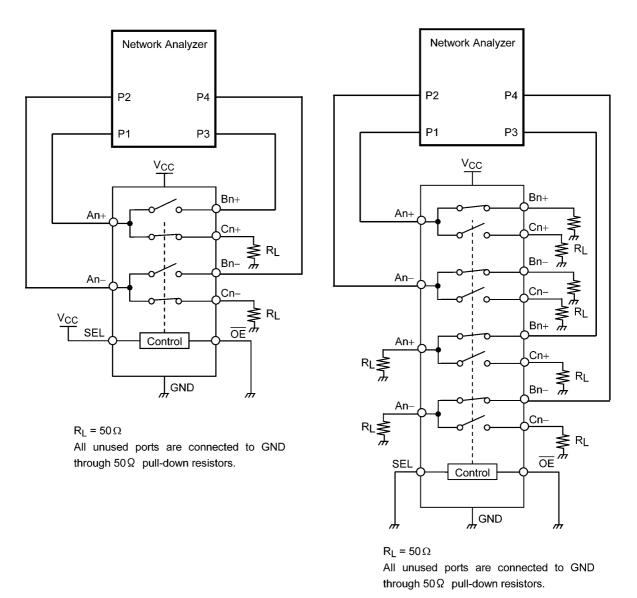
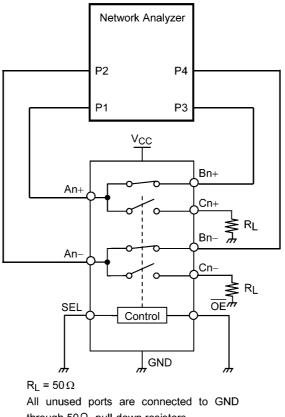


Fig. 12.6 Differential OFF isolation

Fig. 12.7 Differential Near-end crosstalk



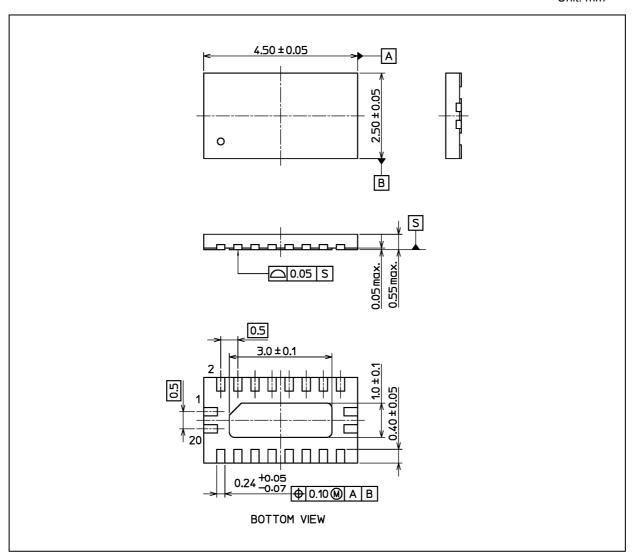
through $50\,\Omega$ pull-down resistors.

Fig. 12.8 Differential return loss, Differential insertion loss, -3dB Bandwidth



Package Dimensions

Unit: mm



Weight: 0.017 g (typ.)

| Package Name(s) |
|---------------------------------|
| TOSHIBA: P-UQFN20-0305-0.50-001 |
| Nickname: TQFN20 |



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Rev.2.0

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